

Muon SORTER ASIC Design

- **Sorter chip design: status of the art**
- **Future plans**

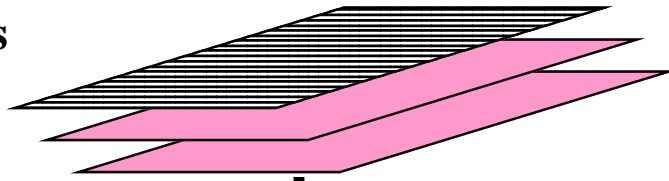
TRIDAS, CERN November 3-6, 1997

RPC trigger segmentation

~200k strips

$\Delta\phi=5/16^\circ$

$\Delta\eta\approx 0.1$



μ recognition

p_t measurement

$33(39)\times 12\times 12=$

$4752(5616)$ segments

PACT
(segment processor)

$\Delta\phi=2.5^\circ$

$\Delta\eta\approx 0.1$

on $396(468)$ boards

$\Delta\phi=30^\circ$

$\Delta\eta\approx 0.1$

TRB
(sector processor)
(2 sort levels)

selection of
4 highest $p_t \mu$
in every ring
 $33(39)$ rings

ring processor
 $\Delta\phi=360^\circ$
 $\Delta\eta\approx 0.1$
(4 sort levels)

$396(468)\times 4$ output

selection of
4 highest $p_t \mu$
in $11(13)$
super ring

RPCs/ring sorter
(2 sort level)
 $\Delta\phi=360^\circ$
 $\Delta\eta\approx 0.35$

$33(39)\times 4$ output

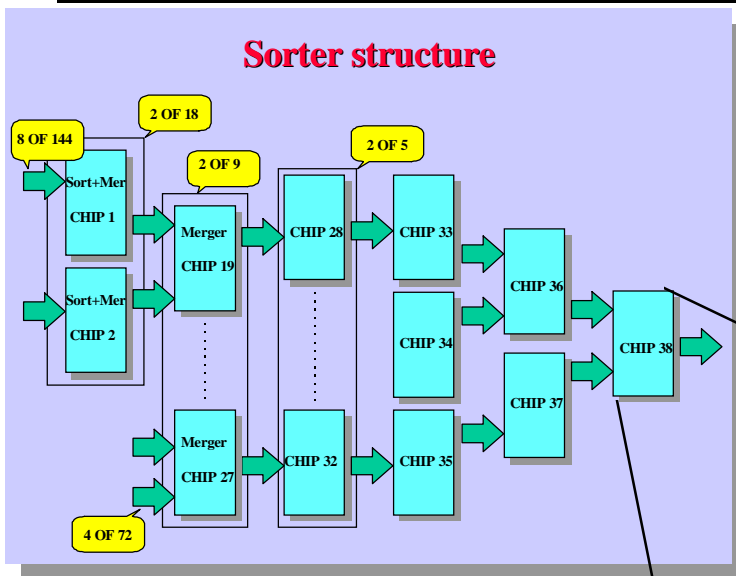
$11(13)\times 4$

Global Muon Trigger
(4 sort levels)

4 output

MUON SORTING TREE

- The Sorting Processor chip selects the highest 4 objects in an 8 objects group
- We need of a “Sorting Network” to read the whole apparatus
- “Tree like structure” subdivided over various levels of processing (8 levels)
- The “trigger latency” assigned for sorting RPC data is 8 BX time slot (200ns)



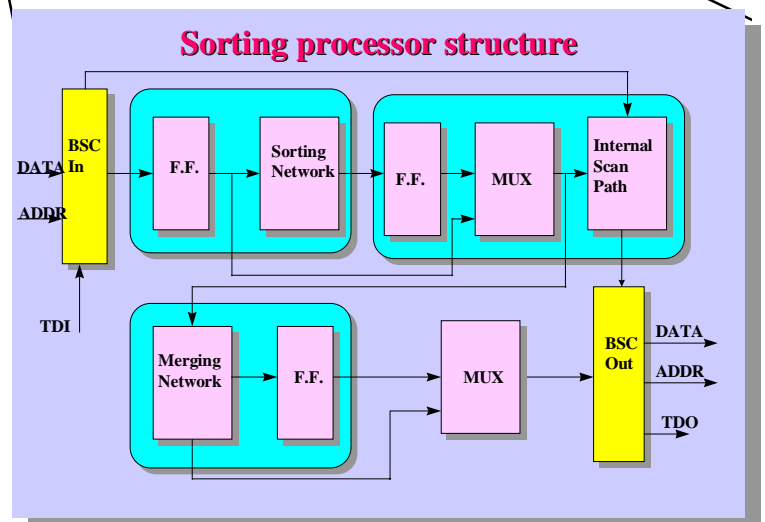
SORTER PROCESSOR CHARACTERISTICS

INPUT	OUTPUT
8 DATA (8 bits)	4 DATA
8 ADDRESSES (8 bits)	4 ADDRESSES

WORD FORMAT

	N. bits
Code	5
Sign	1
Quality	2

1st level: SORTER+MERGER 2 bx
 next levels: MERGER 1 bx
 last level: MERGER+FF 2 bx



SORTING PROCESSOR CHARACTERISTICS

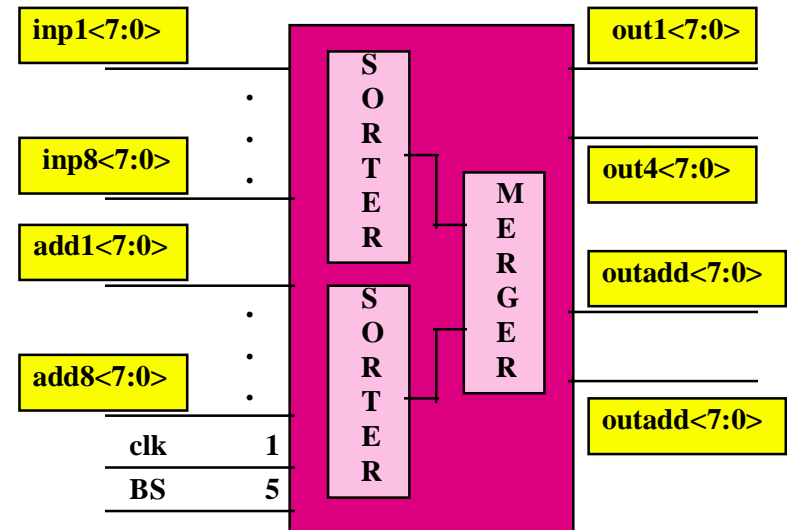
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WORD FORMAT

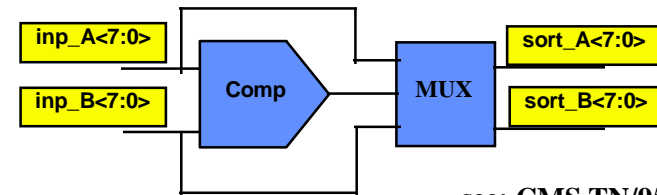
	N. bits
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Sorting Processor Chip

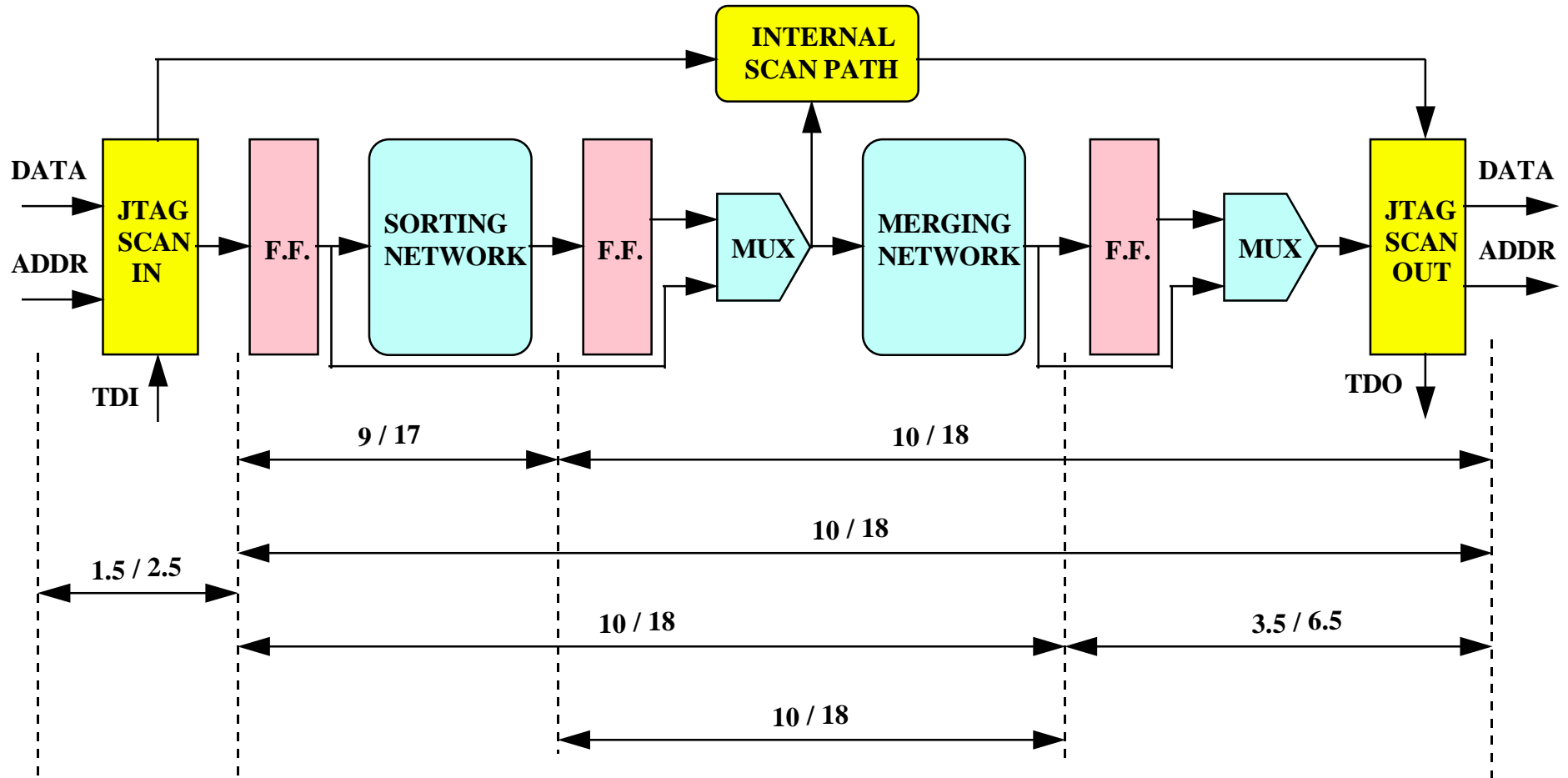


Basic element of Sorting Processor

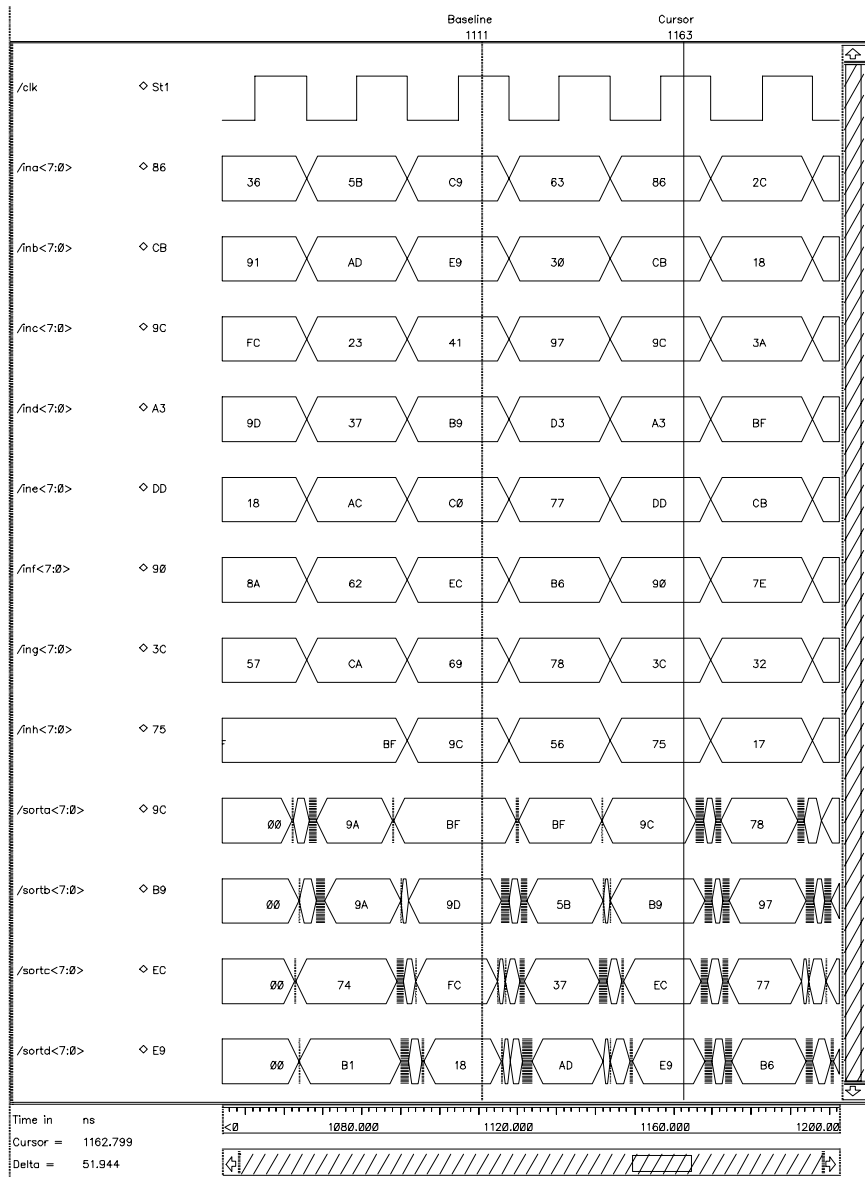


see: CMS TN/95-028

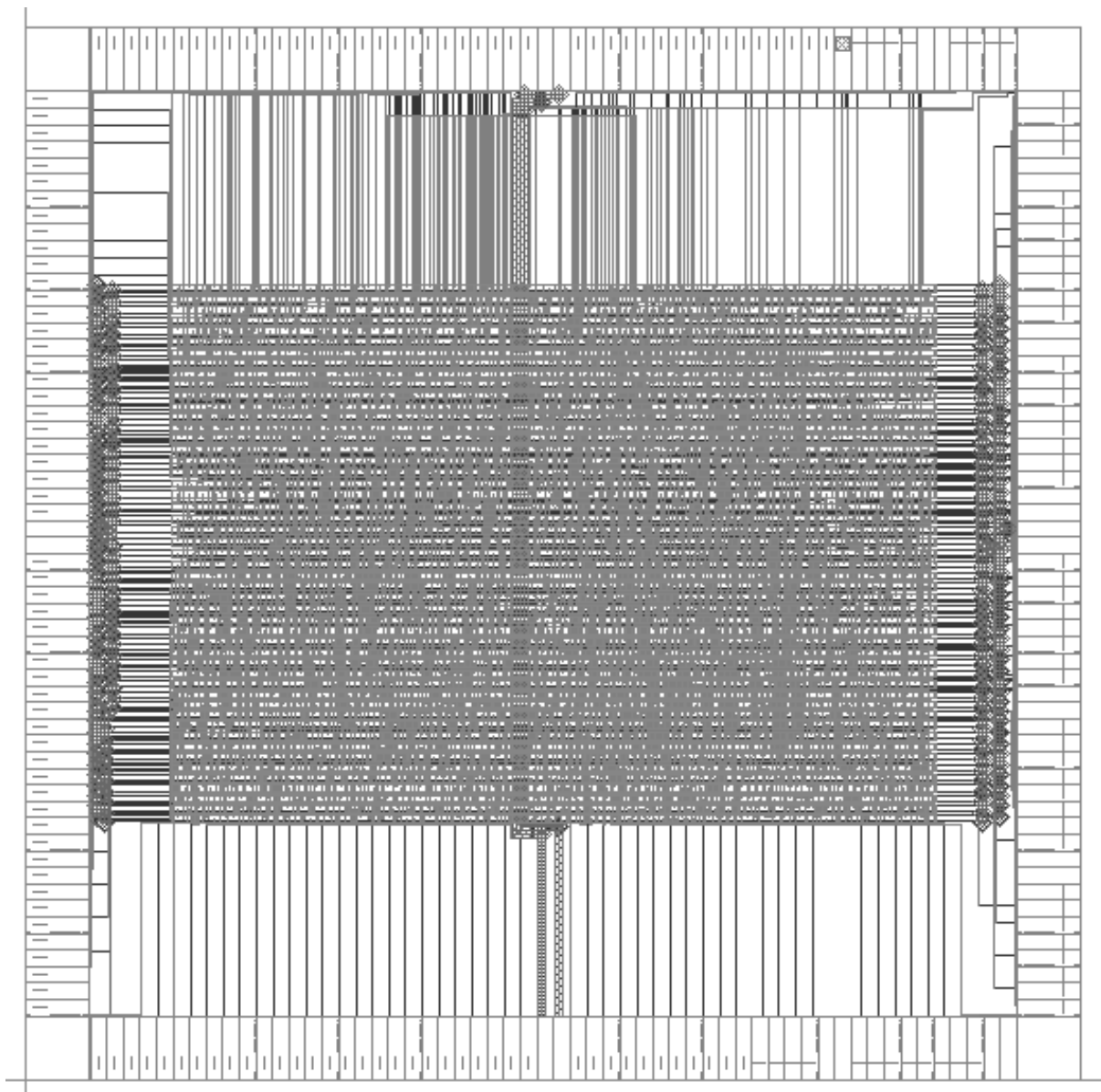
SORTER BLOCK DIAGRAM



ALL DELAYS ARE EXPRESSED IN NS (TYP / MAX)



Typical SORTER + MERGER Verilog simulation



- **Digital semi-custom ASIC using 0.8 μm Bi-CMOS technology by AMS**
- **224 I/O and power pins**
- **JTAG IEEE 1149.1**
- **area: 7.5x7.5 mm²**
- **40 MHz clock**
- **prototype developing cost: 2600 FF/ mm²**
- **prototype developing & production by CMS**

RPC Trigger Test Bench

-Designed a Trigger Test Bench made by:

- **Input Board**
- **Synchronization Board**
- **Trigger Board**
- **Read-Out Board**
- **Control & Clock Generator Board**

-installed and tested successfully on an RPC telescope built in BARI (Oct. '96)

-every logic devices was realized with programmable devices (PAC on ALTERA and XILINX for Sorter)

-new trigger electronics for test will be prepared next year mounting the final version of ASICs for PAC & Sorter

Conclusions

- **Prot chip will be delivered next January**
- **Design of a Test Board beginning '98**
- **Integration in new TRB 2'nd half '98**
- **Order for production during '99**

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